L Number	Hits	Search Text	DB	Time stamp
1	1	@ad<=20020109 and 'copper wiring bond pad' same 'IMD'	USPAT; US-PGPUB;	2004/05/14 11:00
2	0	<pre>@ad<=20020109 and 'copper wiring' same 'alumimun' same 'bond pad' same 'IMD'</pre>	EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/05/14 10:54
3	0	<pre>@ad<=20020109 and 'copper wire' same 'alumimun' same 'bond pad' same 'IMD'</pre>	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/05/14 10:54
4	0	<pre>@ad<=20020109 and 'copper wire' same 'alumimun' same 'bond pad' same 'intermetal dielectric layer'</pre>	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/05/14 11:07
5	6	@ad<=20020109 and 'bond pad' same 'intermetal dielectric layer'	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/05/14 10:55
6	22	@ad<=20020109 and 'wiring bond pad'	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/05/14 11:06
7	0	@ad<=20020109 and 'under pad' and 'copper' with 'buffer' and 'IMD'	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/05/14
8	0	@ad<=20020109 and 'copper' with 'Al buffer' and 'IMD'	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/05/14 11:07
9	772	@ad<=20020109 and 'intermetal dielectric layer'	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/05/14
10	14	@ad<=20020109 and 'intermetal dielectric layer' and 'bond pads'	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/05/14 11:27
11	2	<pre>@ad<=20020109 and 'intermetal dielectric layer' and 'copper' adjl 'connection pads'</pre>	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/05/14 11:19
12	13	<pre>@ad<=20020109 and 'reinforce' with 'bond pads'</pre>	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/05/14
_	2054	(438/612).ccls. or (438/597).ccls. and @ad<=20020109	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/12/30 10:09
_	337 -	((438/612).ccls. or (438/597).ccls. and @ad<=20020109) and copper and aluminum	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/08/21 11:04

Search History 5/14/04 11:58:12 AM Page 1

-	74		USPAT;	2003/01/23
		@ad<=20020109) and 'bonding pad' with	US-PGPUB;	10:01
		'integrated circuit'	EPO; JPO;	
			DERWENT; IBM TDB	
_	1	((438/612).ccls. or (438/597).ccls. and	USPAT;	2002/08/21
	_	@ad<=20020109) and Cu adj bonding adj pad	US-PGPUB;	11:13
		with 'integrated circuit'	EPO; JPO;	
			DERWENT;	·
			IBM_TDB	
-	6	((438/612).ccls. or (438/597).ccls. and	USPAT;	2002/08/21
		@ad<=20020109) and Copper adj bonding adj	US-PGPUB;	11:14
		pad	EPO; JPO; DERWENT;	
			IBM TDB	
_	1143	@ad<=20020109 and cu adj 'bonding pad'	USPAT;	2003/12/22
		with 'IMD' or 'intermetal dielectric'	US-PGPUB;	12:10
			EPO; JPO;	
			DERWENT;	
	_		IBM_TDB	
-	0	, oan :	USPAT;	2004/05/14
		with 'IMD'	US-PGPUB;	10:46
			EPO; JPO; DERWENT;	
			IBM TDB	
_	0	@ad<=20020109 and cu adj 'bonding pad'	USPAT;	2003/12/22
		with 'intermetal dielectric'	US-PGPUB;	12:00
			EPO; JPO;	
			DERWENT;	
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~	6	@ad<=20020109 and cu adj 'bonding pad'	USPAT; US-PGPUB;	2003/01/23 09:03
		WICH AI	EPO; JPO;	09.03
1			DERWENT;	
			IBM TDB	
_	3	1 0	USPĀT;	2002/08/21
		and 'IMD'	US-PGPUB;	11:43
			EPO; JPO;	
			DERWENT; IBM TDB	
_	1	"3942245".PN.	USPAT	2002/08/21
		3342243 .114.	051111	11:40
_	1	"5075965".PN.	USPAT	2002/08/21
				11:40
-	1	"5288006".PN.	USPAT	2002/08/21
		#527/025# py	,,,ср,, ш	11:40
-	1	"5376235".PN.	USPAT	2002/08/21 11:41
_	1	"5384284".PN.	USPAT	2002/08/21
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_	1	"5436412".PN.	USPAT	2002/08/21
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		pad with 'intermetal dielectric'	US-PGPUB;	09:52
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			IBM TDB	
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		pad and 'intermetal dielectric'	US-PGPUB;	11:46
			EPO; JPO;	
			DERWENT;	
		(220 /100 21) CGTS	IBM_TDB	2002/08/21
-	809	(228/180.21).CCLS.	USPAT; US-PGPUB;	2002/08/21 11:48
			EPO; JPO;	11.70
1	1		DERWENT;	
			IBM TDB	
-	93	((228/180.21).CCLS.) and bonding adj pad	USPAT;	2002/08/21
1			US-PGPUB;	11:50
			EPO; JPO;	
1			DERWENT;	
	L	<u> </u>	IBM TDB	<u> </u>

-	9	((228/180.21).CCLS.) and bonding adj pad	USPAT;	2002/08/21
		with copper	US-PGPUB;	13:32
			EPO; JPO;	
			DERWENT;]
			IBM_TDB	
-	8	((228/180.21).CCLS.) and bond adj pad	USPAT;	2002/08/21
		with copper	US-PGPUB;	13:30
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	0	((228/180.21).CCLS.) and bond adj pad	USPAT;	2003/01/23
		with copper with 'Al' adj buffer	US-PGPUB;	08:45
			EPO; JPO;	
			DERWENT;	l
		//220/100 21) ggrg)1 }111	IBM_TDB	0000 (00 (01
_	0	((228/180.21).CCLS.) and bond adj pad	USPAT;	2002/08/21
		with copper with 'Al'	US-PGPUB;	13:31
			EPO; JPO;	
			DERWENT;	
	630		IBM_TDB	2002/08/21
-	639	@ad<=20010119 and bonding adj pad with	USPAT;	2002/08/21
		copper	US-PGPUB;	13:36
			EPO; JPO;	
	1		DERWENT;	
	350	0-4(-20010110 4	IBM_TDB	0000 (00 (01
-	359	@ad<=20010119 and bonding adj pad with	USPAT;	2002/08/21
		copper and aluminum	US-PGPUB;	13:47
1			EPO; JPO;	
			DERWENT;	
	30	0-4-20010110	IBM_TDB	2002/00/21
-	30	@ad<=20010119 and copper adj bonding adj	USPAT;	2002/08/21
		pad and aluminum	US-PGPUB;	13:59
	!		EPO; JPO;	
			DERWENT;	
	020	0-d-20010110 and handing add and and	IBM_TDB	2002/08/21
_	839	<pre>@ad<=20010119 and bonding adj pad and aluminum and buffer</pre>	USPAT;	2002/08/21
		aluminum and buller	US-PGPUB;	14:00
			EPO; JPO;	
			DERWENT; IBM TDB	
1_	4120	'bonding pad' and apparatus	USPAT;	2002/08/21
	4120	bonding pad and apparacus	US-PGPUB;	15:03
			EPO; JPO;	13.03
			DERWENT;	
			IBM TDB	
1_	3573	((257/459) or (257/676) or (257/786) or	USPAT;	2002/08/21
	33,3	(237/433) of (237/670) of (237/760) of (237/760)	US-PGPUB;	15:07
		,,	EPO; JPO;	
			DERWENT;	
			IBM TDB	
-	1779	(438/612).ccls. and @ad<=20020109	USPAT;	2003/01/23
	1,.,	(,,	US-PGPUB;	08:47
1			EPO; JPO;	
			DERWENT;	
1	1		IBM TDB	
1 -	1	bond adj pad with copper with 'Al' and	USPAT;	2003/01/23
	_	'buffer'	US-PGPUB;	08:46
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
1 -	11	'bond' and 'pad' with copper with 'Al'	USPĀT;	2003/01/23
		and 'buffer'	US-PGPUB;	08:54
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	284	(438/48).ccls. and @ad<=20020109	USPAT;	2003/01/23
1			US-PGPUB;	08:47
			EPO; JPO;	
			DERWENT;	
			IBM TDB	

	1555	1 (100 (51 (1)))		
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	1		IBM TDB	
_	573	(257/459).ccls. and @ad<=20020109	USPAT;	2003/08/05
	3,3	(257/405):CC15: and Gad(-20020109	US-PGPUB;	10:35
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			DERWENT;	
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1 -	1222	(257/784).ccls. and @ad<=20020109	USPAT;	2003/08/05
			US-PGPUB;	10:37
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
-	1209	(257/786).ccls. and @ad<=20020109	USPAT;	2003/08/05
			US-PGPUB;	10:39
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
-	735	(257/781-782).ccls. and @ad<=20020109	USPAT;	2003/08/05
1			US-PGPUB;	10:40
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			DERWENT;	
1			IBM_TDB	
-	1392	(257/774).ccls. and @ad<=20020109	USPAT;	2003/01/23
			US-PGPUB;	11:44
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	1	'bond pad' with 'copper' with 'Al' and	USPAT;	2003/01/23
		'buffer'	US-PGPUB;	08:55
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	0000 (01 (00
-	1	'bonding pad' with 'copper' with 'Al' and	USPAT;	2003/01/23
		'buffer'	US-PGPUB;	08:56
			EPO; JPO;	
			DERWENT; IBM TDB	
	122	'bonding pad' with 'Cu' with 'Al'	USPAT;	2003/01/23
-	122	bonding pad with 'Cu with Ai	US-PGPUB;	09:05
			EPO; JPO;	""
			DERWENT;	
			IBM TDB	
_	117	@ad<=20020109 and 'bonding pad' with 'Cu'	USPAT;	2003/01/23
1	'''	with 'Al'	US-PGPUB;	09:01
1			EPO; JPO;	
			DERWENT;	
			IBM TDB	
-	6	@ad<=20020109 and cu adj 'bonding pad'	USPAT;	2003/01/23
		with 'Al'	US-PGPUB;	09:03
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	117	@ad<=20020109 and 'bonding pad' with 'Cu'	USPAT;	2003/08/05
		with 'Al'	US-PGPUB;	11:18
1			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
] -	1	"4811081".PN.	USPAT	2003/01/23
		HE COAF 40 H		09:57
-	1	"5001542".PN.	USPAT	2003/01/23
	_			09:57
1-	1	"6108212".PN.	USPAT	2003/01/23
	_	(0.641.20	HCDrm	09:57
-	1	"6064120".PN.	USPAT	2003/01/23
L	I		<u></u>	09:58

- 246 @ad<=20020109 and 'bonding pad' with 'integrated circuit' and 'Cu' and 'Al' USPAT; USP-05PUB; EPO; JPO; DEWENTT; IBM TDB USPAT; USP-05PUB; EPO; JPO; DEWENTT; IBM TDB USPAT; USP-05PUB; EPO; JPO; DEWENTT; IBM TDB USPAT; USP-05PUB; EPO; JPO; DEWENT; IBM TDB USPAT; USP-05PUB; EPO	
Copper and aluminum Sepo; JPO; DERWENT; IBM TDB USPAT; US-FGPUB; BPO; JPO; DERWENT; IBM TDB USPAT; US-	
DERWENT; LBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; LBM TDB USPAT; US-PGPUB; DERWENT; LBM T	
- 231 (257/784).ccls. and @ad<=20020109 and USPAT; US-PGPUB; BPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; BPO;	
- 231 (257/784).ccls. and @ad<=20020109 and USPĀT; 2003/01/23 10:38 10:39 10:38 10:39 10:3	
Copper' and 'aluminum'	
Company	
DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; JPO; DERWENT	
-	
- 2356 (438/612).ccls. or (438/597).ccls. and USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; 2003/08/05 US-PGPUB; 2003/08/05 US-PGPUB; 2003/08/05 US-PGPUB; 2003/08/05 US-PGPUB; 2003/08/05 US-PGPUB; 2003/08/05 US-PGPUB; 2003/08/	
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DERWENT; IBM_TDB USPAT; 2003/08/05 10:35	
T98 (228/180.21).ccls. and @ad<=20020109 IBM_TDB 2003/08/05 10:36 10:36	
- 798 (228/180.21).ccls. and @ad<=20020109	
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EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM	
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TBM_TDB	
- 2531 (438/613-617).ccls. and @ad<=20020109 USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	
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EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; US-PGPUB; US-PGPUB; US	
DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB;	
- 586 (257/459).ccls. and @ad<=20020109	
- 1320 (257/459).ccls. and @ad<=20020109	
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- 1320 (257/784).ccls. and @ad<=20020109 IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; US-PGPUB; EPO; USPAT; US-PGPUB; EPO; US-PGPUB; EPO; USPAT; US-P	
- 1320 (257/784).ccls. and @ad<=20020109 USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; 2003/08/05 10:42 - 782 (257/781-782).ccls. and @ad<=20020109 USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; 2003/08/05 US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	
US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; IBM_TDB USPAT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	
- 1288 (257/786).ccls. and @ad<=20020109	
- 1288 (257/786).ccls. and @ad<=20020109	
- 1288 (257/786).ccls. and @ad<=20020109 IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; US-PGP	
- 1288 (257/786).ccls. and @ad<=20020109 USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	
US-PGPUB; EPO; JPO; DERWENT; IBM_TDB US-PGPUB; EPO; JPO; US-PGPUB; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	
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- 782 (257/781-782).ccls. and @ad<=20020109 IBM_TDB	
- 782 (257/781-782).ccls. and @ad<=20020109 USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	
US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	
EPO; JPO; DERWENT; IBM_TDB - 1782 (257/676).ccls. and @ad<=20020109 USPAT; 2003/08/05 US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	•
DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	
- 1782 (257/676).ccls. and @ad<=20020109 IBM_TDB	
- 1782 (257/676).ccls. and @ad<=20020109 USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	
US-PGPUB; 10:46 EPO; JPO; DERWENT; IBM_TDB	
EPO; JPO; DERWENT; IBM_TDB	
DERWENT; IBM_TDB	
1 - 1 - 1 - 1 - 1 - 1 - 1 - 1 - 1 - 1 -	
- 27 @ad<=20020109 and 'bonding pad' near3 USPAT; 2003/08/05	
Cu' with 'Al' US-PGPUB; 11:19	
EPO; JPO;	
DERWENT;	
IBM_TDB	
- 63 @ad<=20020109 and 'bonding pad' near3 USPAT; 2003/08/05	
'Copper' with 'Aluminum' US-PGPUB; 11:32	
EPO; JPO;	
DERWENT; IBM TDB	
- 34 @ad<=20020109 and CVC.as. and USPAT; 2003/08/05	
interconnect US-PGPUB; 11:34	
EPO; JPO;	
DERWENT;	
IBM TDB	
- 1 ("6333559").PN. USPAT 2003/08/05	
11:38	
- 4 (("5785236") or ("6197613") or USPAT 2003/08/05	
("6162652") or ("6555759")).PN. 11:40	
- 0 "20020164840" USPAT 2003/08/05	
11:41	

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_	0	"2002/0164840"	USPAT	2003/08/05
_	2	"20020164840"	USPAT;	2003/08/05
			US-PGPUB;	11:42
			EPO;	
			DERWENT;	
l_	2	"20010035452"	IBM_TDB USPAT;	2003/08/05
	2	20010033432	US-PGPUB;	11:43
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			DERWENT;	
	_		IBM_TDB	
_	2	"20020047218"	USPAT;	2003/08/05
			US-PGPUB; EPO;	11:43
			DERWENT;	
			IBM TDB	
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		,	US-PGPUB;	11:23
			EPO; JPO;	
			DERWENT; IBM TDB	
1-	2	"20030127716"	USPAT;	2003/12/22
	J		US-PGPUB;	11:23
Ì			EPO; JPO;	
			DERWENT;	
	0		IBM_TDB	2002/12/22
-	0	<pre>@ad<=20020109 and 'wiring bonding pad' and 'intermetal dielectric' and 'metal</pre>	USPAT; US-PGPUB;	2003/12/22
1		layer'	EPO; JPO;	12.04
		24102	DERWENT;	
			IBM_TDB	
	0	•	USPAT;	2003/12/22
		and 'intermetal dielectric'	US-PGPUB;	12:04
			EPO; JPO; DERWENT;	
1			IBM TDB	
-	209	@ad<=20020109 and 'wiring bonding pad'	USPAT;	2003/12/22
			US-PGPUB;	12:10
			EPO; JPO;	
			DERWENT; IBM TDB	
_	22	@ad<=20020109 and 'wiring bond pad'	USPAT;	2003/12/22
		caa abbabbb ana willing soma paa	US-PGPUB;	12:04
			EPO; JPO;	
			DERWENT;	
	4.4		IBM_TDB	2002/12/22
] -	44	<pre>@ad<=20020109 and 'copper' and 'bonding pad' and 'IMD'</pre>	USPAT; US-PGPUB;	2003/12/22
		paa ana m	EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	40		USPAT;	2003/12/22
		pads' and 'IMD'	US-PGPUB; EPO; JPO;	12:48
			DERWENT;	
-			IBM TDB	
-	69	@ad<=20020109 and 'bond pads' and 'IMD'	USPĀT;	2003/12/22
			US-PGPUB;	12:54
]			EPO; JPO;	
[DERWENT; IBM TDB	
-	107	@ad<=20020109 and 'bond pads' same	USPAT;	2003/12/22
['mechanical stress'	US-PGPUB;	12:59
			EPO; JPO;	
[DERWENT;	
<u> </u>	108	 @ad<=20020109 and 'bonding pad' same	IBM_TDB USPAT;	2003/12/22
	100	'mechanical stress'	US-PGPUB;	12:59
			EPO; JPO;	'
			DERWENT;	
			IBM TDB	

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-	1	@ad<=20020109 and 'bond pads' same	USPAT;	2003/12/23
		'buffer layer' same 'bonding layer'	US-PGPUB;	09:54
			EPO; JPO;	
			DERWENT;	
		•	IBM TDB	
1 -	1	@ad<=20020109 and 'bonding pad' same	USPAT;	2003/12/23
		'buffer' same 'bonding layer'	US-PGPUB;	09:57
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
_	13	@ad<=20020109 and 'UBM' and 'bond pads'	USPĀT;	2003/12/23
	**	and 'buffer' and 'bonding'	US-PGPUB;	10:00
		and buffer and bonding	EPO; JPO;	10.00
	ļ		DERWENT;	
	407	And and then the delegate and IRRA	IBM_TDB	2002/12/22
-	497	@ad<=20020109 and 'bond pads' and 'EDS'	USPAT;	2003/12/23
			US-PGPUB;	10:12
			EPO; JPO;	
			DERWENT;	
	_		IBM_TDB	
-	2	@ad<=20020109 and 'bond pads' with 'EDS'	USPAT;	2003/12/23
			US-PGPUB;	10:03
			EPO; JPO;	1
			DERWENT;	
			IBM_TDB	
-	315	chou.in. and taiwan	USPAT;	2003/12/23
			US-PGPUB;	10:06
			EPO; JPO;	
1			DERWENT;	
			IBM TDB	
_	l. 0	chou-kuo.in.	USPAT;	2003/12/23
			US-PGPUB;	10:04
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
l _	25	kuo-yu.in.	USPAT;	2003/12/23
			US-PGPUB;	10:06
			EPO; JPO;	
			DERWENT;	
	J		IBM TDB	
_	1 1	@ad<=20020109 and 'single layer' near	USPAT;	2003/12/23
_	1	'wiring bond pad'	US-PGPUB;	10:13
		willing bond pad	EPO; JPO;	10.13
			DERWENT;	
	1	0.d<-20020100 and 1	IBM_TDB USPAT;	2003/12/23
-	22	@ad<=20020109 and 'wiring bond pad'		
1			US-PGPUB;	10:13
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	0000 (10 (55
-	2	("6378759").PN.	USPAT;	2003/12/30
			US-PGPUB;	10:09
	1		EPO; JPO;	
			DERWENT;	
			IBM_TDB	